

Application Serial No. 10/826,034
Reply to Office Action of July 26, 2005

PATENT
Docket: CU-3692

ARGUMENTS

Reconsideration of the above-identified application is respectfully requested.

The Examiner objected to the Specification as having a title of the invention that was not descriptive. The title of the invention provided by this amendment is believed to overcome the Examiner's objection.

Claims 1-15 were rejected under 35 U.S.C. §102(a) as being anticipated by U.S. publication number 2003/00116857 to Taniguchi et al., hereafter "Taniguchi."

Independent claims 1 and 10 have been amended to add the step of "thin-filming" a semiconductor wafer and to recite that the step of forming of a through-hole takes place after the step of "thin-filming." Support for these new limitations can be found in the first full paragraph of page 10 of the specification as filed.

Claims 1 and 10 have also been amended to recite that the conducting layer is formed using either a metal plate or a metal foil and that the conductive member is formed by plating as well as being formed *in* the through-hole. Support for these limitations can be found on pages 13 and 14 of the specification.

Claims 2, 3, 11 and 12 have been cancelled.

It should be noted too, Taniguchi does *not* disclose the limitations of claims 1 and 10 as filed. In particular, the Examiner's attention is directed to the first and third limitation of both claims 1 and 10, which limitations require that a semiconductor be attached to and separated from a "supporting member" respectively. (See claims 1 and 10 as filed.)

In the Office Action, the Examiner asserted that element 32 of Taniguchi corresponds to the "first supporting member" that is recited in both claims 1 and 10.

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The Examiner asserted that FIG. 2 B of Taniguchi shows the separation of the semiconductor from the first supporting member.

Paragraph [0061] of Taniguchi clearly states that element 32 is a "resist film." A "resist film" is well known to be very thin film, which acts as a mask. A "resist film" is not a supporting member nor is it attached to the bottom of semiconductor. FIG. 2B is described in paragraph [0063] and does *not* show the separation of a semiconductor from a supporting element or structure.

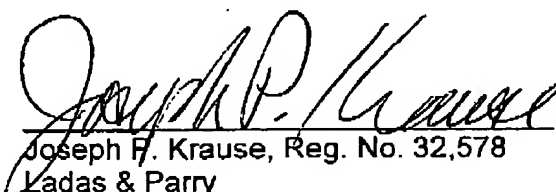
Unless the Examiner can show how a "resist film 32" satisfies the "first supporting member" limitation of claims 1 and 10, the rejection of claims 1 -15 should be withdrawn.

Because claims 1 and 10 as amended avoid the Taniguchi reference and because Taniguchi doesn't actually show each and every limitation of claims 1 and 10, claims 1 and 10 are allowable. Claims that depend on claims 1 and 10 are therefore also allowable.

For the reasons set forth above, the Applicant submits that claims 1-15 are in condition for allowance.

Respectfully submitted,

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